rev 1.1 22.01.2015

# SMB1N-940-02

- Infrared High Power LED
- 940 nm, 120 mW
- SMD package, PA9T
- Dimension: 5.0 x 5.2 x 5.5 mm
- Viewing Angle: 24°





# Description

SMB1N-940-02 is a surface mount AlGaAs High Power LED with a typical peak wavelength of 940 nm and radiation of 120 mW. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

# Maximum Ratings (TCASE=25°C)

Danamatan	Cumbal	Val	1126	
Parameter	Symbol	Min.	Max.	Unit
Power Dissipation	$P_D$		1000	mW
Forward Current	IF		600	mA
Pulse Forward Current *1	I <sub>FP</sub>		2000	mA
Reverse Voltage	$V_F$		5	V
Thermal Resistance	$R_{THJA}$		10	K/W
Junction Temperature	$T_J$		100	°C
Operating Temperature	$T_{CASE}$	- 40	+ 85	°C
Storage Temperature	$T_{STG}$	- 40	+ 100	°C
Lead Solder Temperature *2	$T_{SLD}$		+ 250	°C

#### **Electro-Optical Characteristics** $(T_{CASE}=25^{\circ}C)$

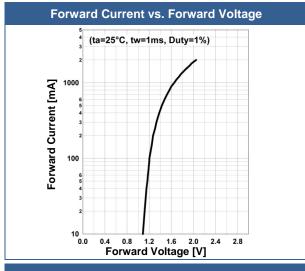
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	$\lambda_P$	I <sub>F</sub> =500mA	930	940	950	nm
Half Width	$\Delta \lambda$	I <sub>F</sub> =500mA		70		nm
Forward Voltage	$V_F$	I <sub>F</sub> =500mA		1.4	1.65	V
	$V_{FP}$	I <sub>FP</sub> =2A		2.0		
Radiated Power *1	Po	I <sub>F</sub> =500mA		120		mW
		I <sub>FP</sub> =2A		460		
Radiant Intensity *2	IE	$I_F=500mA$		240		mW/sr
		I <sub>FP</sub> =2A		920		
Viewing Angle	φ	I <sub>F</sub> =100mA		24		deg.
Rise Time	$t_R$	I <sub>F</sub> =500mA		4000		ns
Fall Time	tϝ	$I_F=500mA$		5000		ns

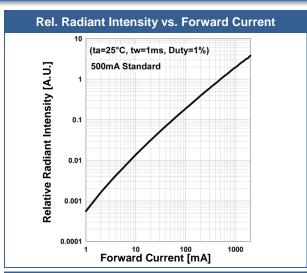
<sup>\*1</sup> measured by S3584-08

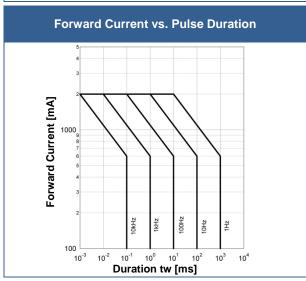
<sup>\*&</sup>lt;sup>1</sup> duty=1%, pulse width = 10 μs \*<sup>2</sup> must be completed within 5 seconds

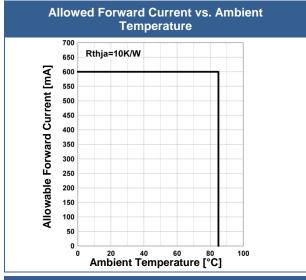
<sup>\*</sup> measured by Tektronix J-6512

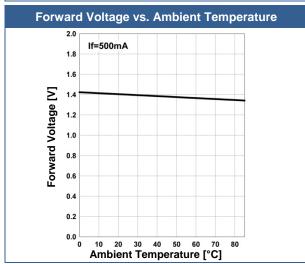
# **Typical Performance Curves**

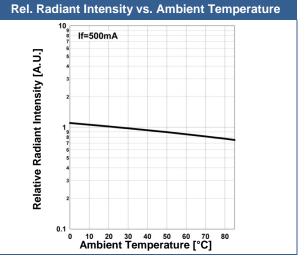










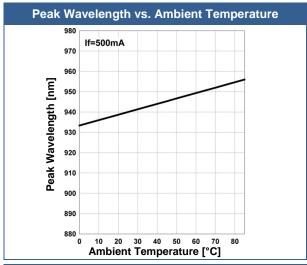


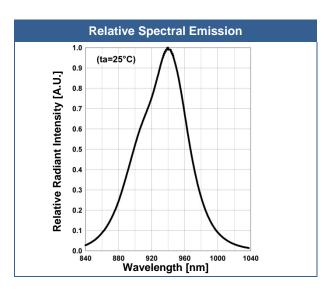


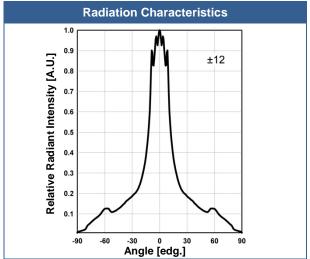
# ROITHNER LASERTECHNIK GmbH

WIEDNER HAUPTSTRASSE 76 IO40 VIENNA AUSTRIA TEL. +43 I 586 52 43 -0, FAX. -44 OFFICE@ROITHNER-LASER.COM

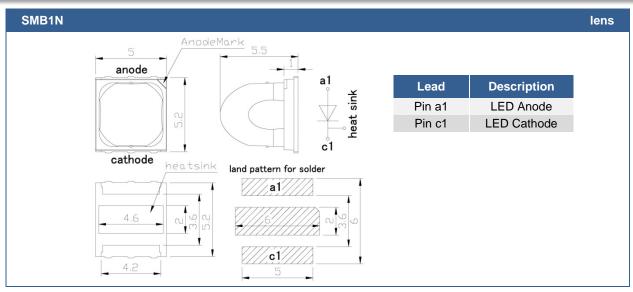








# **Outline Dimensions**



All Dimensions in mm

# **Precautions**

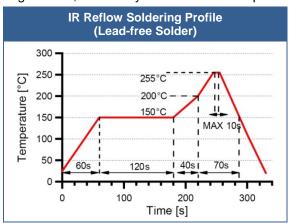
## Soldering:

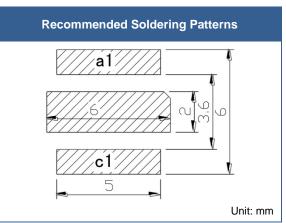
- · Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

### Recommended soldering conditions:

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

### Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

### Static Electricity:

**LEDs are sensitive to electrostatic discharge (ESD)**. Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

### Radiation:

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

### Operation:

## Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

The above specifications are for reference purpose only and subjected to change without prior notice

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